# SOT1934-1

## HLLGA17R, thermal enhanced low profile land grid array package, 17 terminals, 0.65 mm pitch, 4 mm x 3 mm x 1.348 mm body

27 June 2019 Package information

## 1 Package summary

| | |
|---|---|
| **Package type descriptive code** | HLLGA17R |
| **Package style descriptive code** | HLLGA (thermal enhanced low profile land grid array) |
| **Package body material type** | P (plastic) |
| **Mounting method type** | S (surface mount) |
| **Issue date** | 18-02-2019 |
| **Manufacturer package code** | 98ASA01096D |

**Table 1. Package summary**

| Parameter | Min | Nom | Max | Unit |
|---|---|---|---|---|
| package length | - | 4 | - | mm |
| package width | - | 3 | - | mm |
| seated height | - | 1.348 | - | mm |
| nominal pitch | - | 0.65 | - | mm |
| actual quantity of termination | - | 17 | - | |

HLLGA17R, thermal enhanced low profile land grid array package, 17 terminals, 0.65 mm pitch, 4 mm x 3 mm x 1.348 mm body

## 2 Package outline

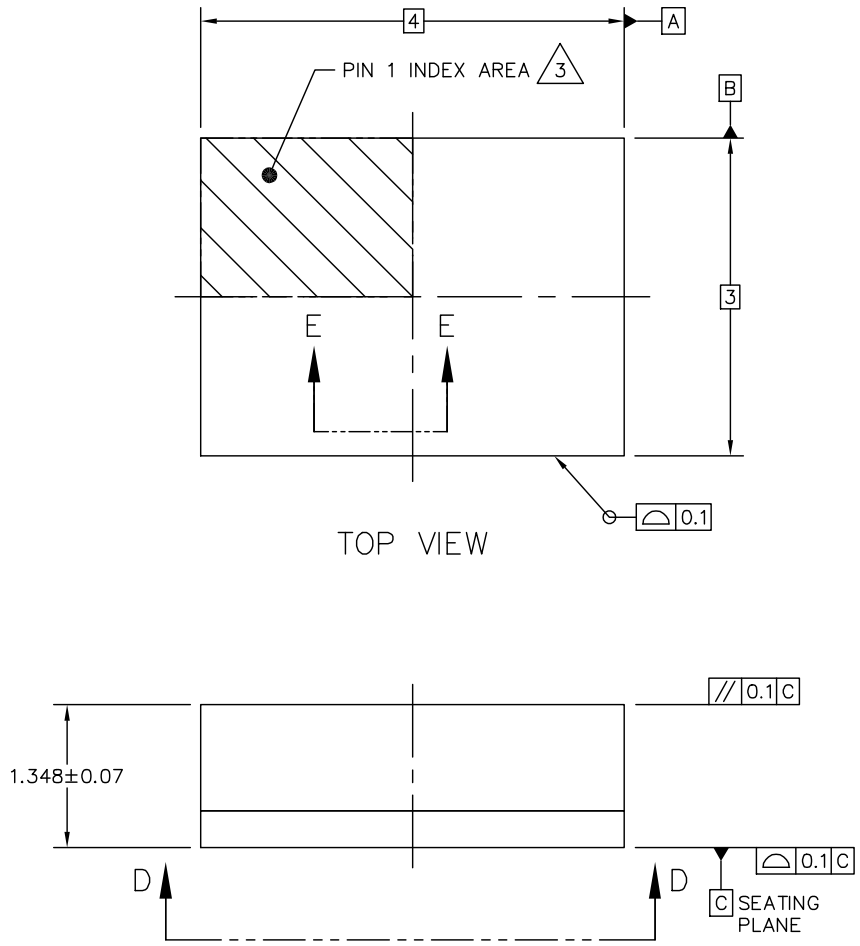



**Figure 1. Package outline HLLGA17R (SOT1934-1)**

## HLLGA17R, thermal enhanced low profile land grid array package, 17 terminals, 0.65 mm pitch, 4 mm x 3 mm x 1.348 mm body

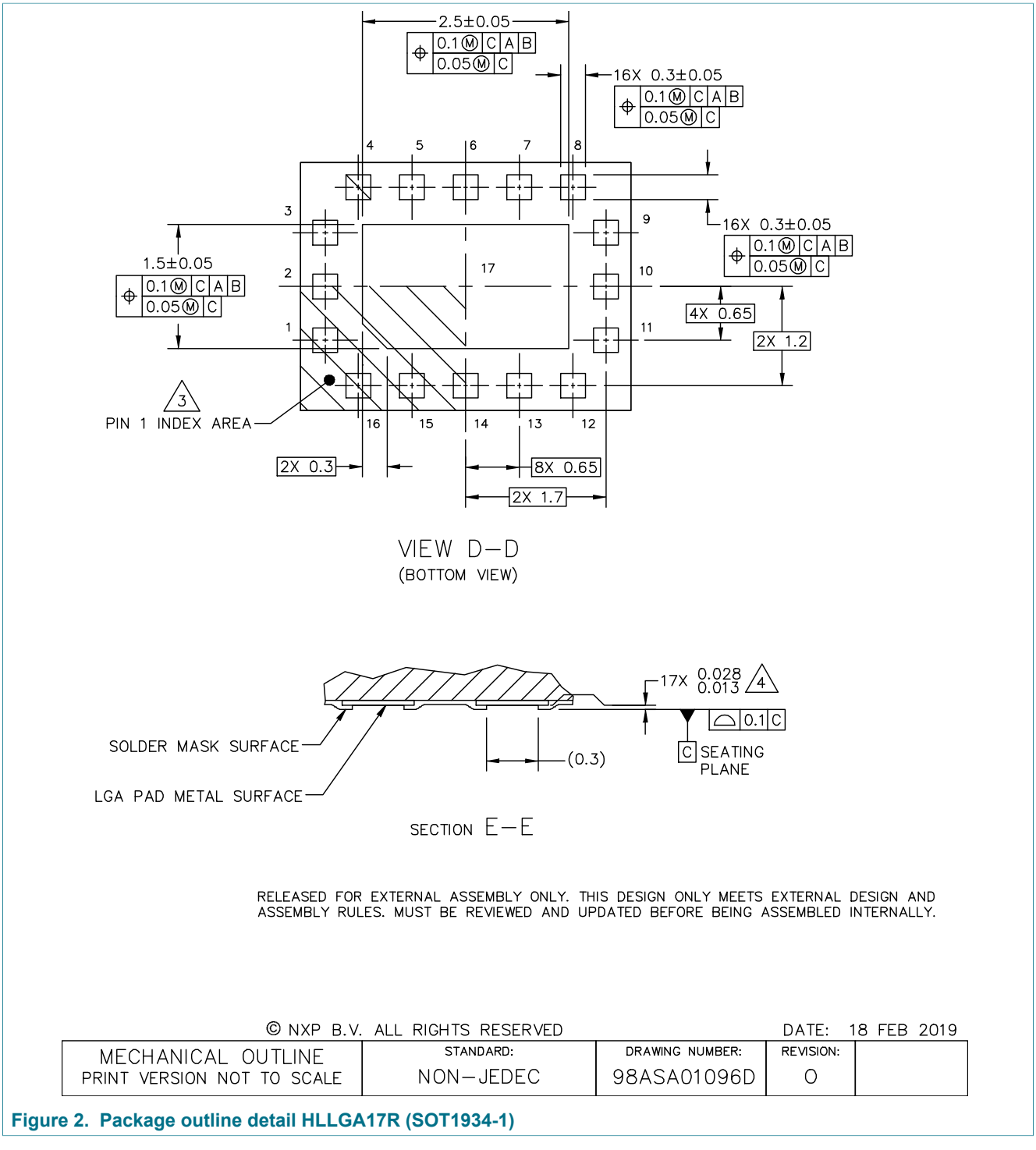
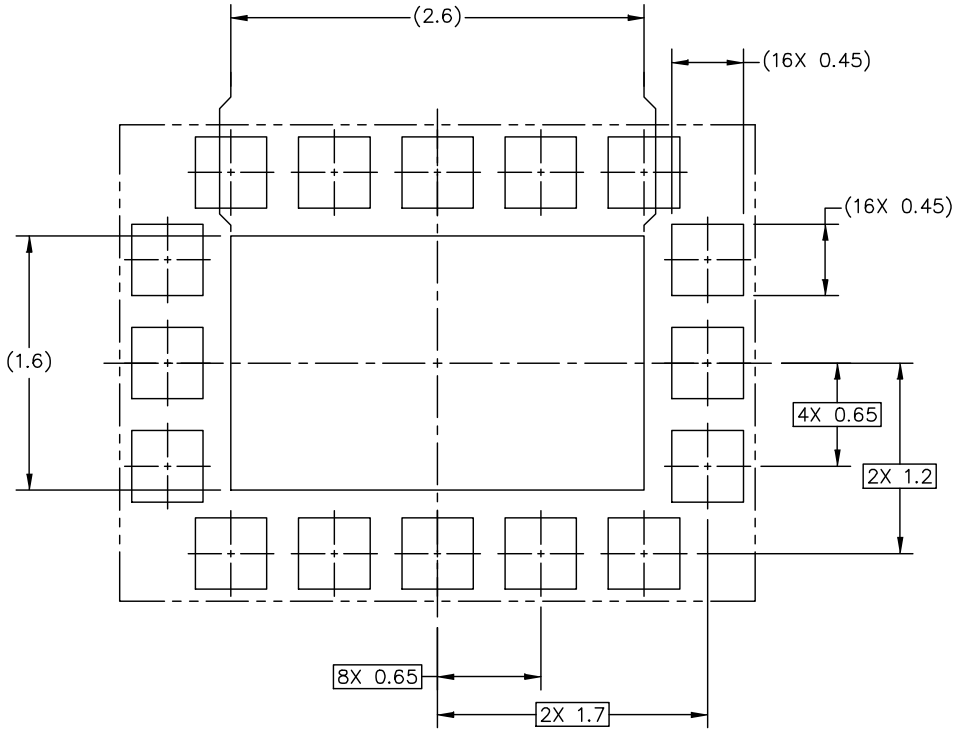



**Figure 2. Package outline detail HLLGA17R (SOT1934-1)**

## 3 Soldering




PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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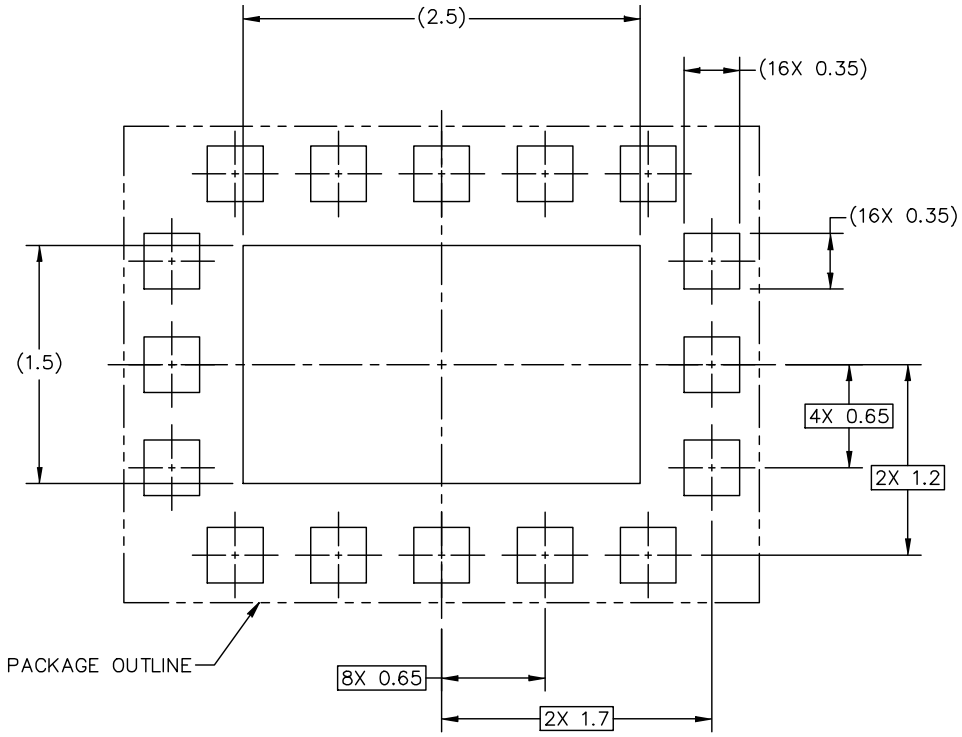
DATE: 18 FEB 2019

| MECHANICAL OUTLINE<br>PRINT VERSION NOT TO SCALE | STANDARD:<br>NON–JEDEC | DRAWING NUMBER:<br>98ASA01096D | REVISION:<br>O | |
|---|---|---|---|---|

**Figure 3. Reflow soldering footprint part1 for HLLGA17R (SOT1934-1)**




PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

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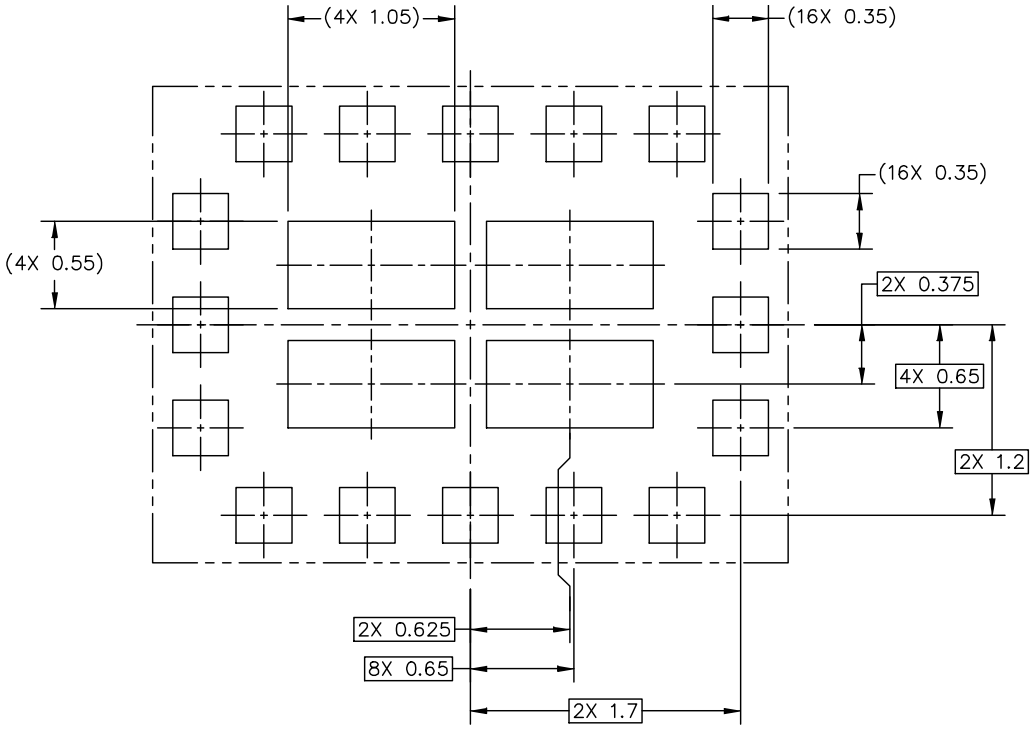
|---|---|---|---|---|

**Figure 4. Reflow soldering footprint part2 for HLLGA17R (SOT1934-1)**




RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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|---|---|---|---|---|

**Figure 5. Reflow soldering footprint part3 for HLLGA17R (SOT1934-1)**


**Figure 6. Package outline note HLLGA17R (SOT1934-1)**

# 4 Legal information

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## Contents





For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

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